

ABSTRACT

An electrical connector semiconductor package with electrically conductive “fly-over” paths wherein semiconductor package hermetically seals one or more substrate comprising one or more semiconductor devices, such as active or passive ICs, and other semiconductor components. Semiconductor package with “fly-over” paths comprises a first package face comprising a first set of connector terminations, such as a set of connector pins that receive a set of incoming external signal. Semiconductor package with “fly-over” paths also comprises a second package face comprising a second set of connector termination, wherein the second set of connector terminations might comprise a set of connector pin cusps to couple to an external board or another connector. One or more of the first set of connector terminations are provided to couple a set of incoming external signals to the one or more semiconductor devices on a substrate via a set of signal pins.